

MKP Film Capacitor

Product Class		Motor /B3235	run round B3232 56*	8*			1				
Date		18/11/2	2019								
IMDS ID if available		NA						States Barans (R) Barans Baran			
Version		5.02.1	a (03/2019)					A off			
Product Part (IMDS: semi component)	Materia (IMDS: Ma	I Class terial)	Material (Classification) VDA 231	Substance			TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)	
Active Part	Thermo	plastic 2A		PP		100	9003-07-0	30.4			
	Light M		1B	Al			6	7429-90-5	1.3		
	Heavy N	<i>l</i> letal	1C	1C Zn			94	7440-66-6	10.4		
Encapsulation	Thermo	plastic 2A		PA 66		100	32131-17-2				
				or PA6			or 50	or 25038-54-4	13.3		
Durome				Melamine Cynurate	lelamine Cynurate			37640-57-6			
		r	2D	Epoxy resin / PU resi	Epoxy resin / PU resin		100	Not available	26.6		
Termination	Heavy Metal		1C	Sn		99.3	7440-31-5	0.8			
				Cu			0.7	7440-50-8	0.1		
	Heavy N	letal 1C		Cu			100	7440-50-8	4.1	Tin	
	Thermo	plastic 2A		PVC			100	9002-86-2	12.2 or 13		
	Heavy N	<i>l</i> letal	1C	Brass(Optional)			100	7440-31-5	0.8		
Sum in total: 1									100		
sizes [.DxH.]	weight rang	je [.g] part numbers sizes [.DxH.] weight range B32328* 30x56 48			e [.g]	part numbers					
35x59	40 66	35x73 93				D32330					
35x73	75 40x95 134										
35x96	96										
45x95	146										
50x96	185										
Not part of a Product Class											
Contact	Perosa, Eduardo					Important remarks:					
Division	CAP FILM, (GTI EPQM)					1) The declaration limit is 0.1% as defined by IEC PAS 61906. Traces are product parts,					
Address	TDK Electronics do Brasil Ltda,					substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated. 2) This Material Data Sheet contains typical values of the respective products set forth					
Bernardo Joaquim Ferreira, 624 – Gravataí, RS, Brazil					2)						
Tel: +55 51 3484 7348 mailto: eduardo.perosa@tdk-electronics.tdk.com.						herein. We expressly point out that all values and statements contained herein are based on our best present knowledge and cannot be regarded as binding statements or binding product specifications, unless otherwise explicitly agreed in writing. TDK ELECTRONICS AG AND ITS AFFILIATES HEREBY EXPRESSLY DISCLAIM ANY REPRESENTATION OR WARRANTY, WHETHER EXPRESS, IMPLIED OR STATUTORY, WITH REGARD TO THE STATEMENTS AND VALUES CONTAINED HEREIN, INCLUDING BUT NOT LIMITED TO ANY REPRESENTATION OR WARRANTY OF MERCHANTABILITY OR SUITABILITY FOR ANY PURPOSE					
*) others: .(not declarable or prohibited substances acc. GADSL) **) typical mass percentage of substance The products set forth herein are "BoHS-compatible" BoHS-compatible											

The products set forth herein are "HoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.



RoHS - Exemptions for the Product Class / Product according to Annex III: (🗹 valid 🗅 not valid)

☑ no exemptions;

Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;

Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;

Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;

Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);

Exemption 7 (c)-I: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;

Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;

Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;

Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;

Other Exemption than above